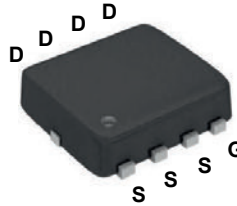
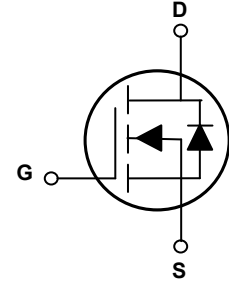


**Main Product Characteristics**

$V_{(BR)DSS}$	40V
$R_{DS(ON)}$	6.2mΩ (Max.)
$I_D$	41A



PPAK3x3



Schematic Diagram

**Features and Benefits**

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



**Description**

The GSGN6R204 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

**Absolute Maximum Ratings** ( $T_A=25^{\circ}C$  unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ Steady-State ( $T_C=25^{\circ}C$ )	$I_D$	41	A
Continuous Drain Current, @ Steady-State ( $T_C=100^{\circ}C$ )		28	A
Pulsed Drain Current ( $T_C=25^{\circ}C$ ) <sup>1</sup>	$I_{DM}$	164	A
Power Dissipation ( $T_C=25^{\circ}C$ ) <sup>2</sup>	$P_D$	39	W
Single Pulse Avalanche Energy <sup>5</sup>	$E_{AS}$	33.6	mJ
Single Pulse Current	$I_{AS}$	11.6	A
Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	40	$^{\circ}C/W$
Junction-to-Case	$R_{\theta JC}$	3.2	$^{\circ}C/W$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +150	$^{\circ}C$
Soldering Temperature (SMD)	$T_{sold}$	260	$^{\circ}C$

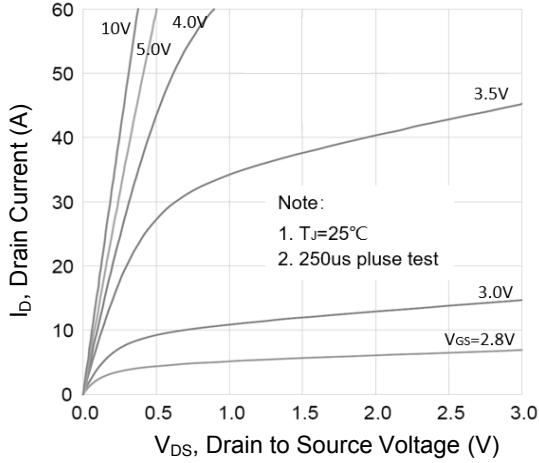
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1.0	$\mu A$
		$V_{DS}=40V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	2.0	-	
Gate-to-Source Forward Leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
Static Drain-to-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	5.1	6.2	m $\Omega$
		$V_{GS}=4.5V, I_D=20A$	-	7.3	9.5	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.1	-	2.8	V
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=15V, f=1\text{MHz}$	-	860	-	pF
Output Capacitance	$C_{oss}$		-	495	-	
Reverse Transfer Capacitance	$C_{rss}$		-	36	-	
Total Gate Charge <sup>3,4</sup>	$Q_g$	$I_D=9A, V_{DD}=15V, V_{GS}=10V$	-	15.5	-	nC
Gate-to-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	3.2	-	
Gate-to-Drain ("Miller") Charge <sup>3,4</sup>	$Q_{gd}$		-	2.2	-	
Gate to Plateau <sup>3,4</sup>	$V_{plateau}$		-	3.3	-	V
Turn-on Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=20V, V_{GS}=10V, R_G=3\Omega, I_D=9A$	-	4.4	-	nS
Rise Time <sup>3,4</sup>	$t_r$		-	31	-	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	21	-	
Fall Time <sup>3,4</sup>	$t_f$		-	12	-	
Gate Resistance	$R_g$	$f=1\text{MHz}$	-	2.2	-	$\Omega$
<b>Source-Drain Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	41	A
Diode Pulse Current	$I_{S,pulse}$		-	-	164	A
Diode Forward Voltage	$V_{SD}$	$I_S=5A, V_{GS}=0V$	-	-	1.4	V
Reverse Recovery Time <sup>3</sup>	$T_{rr}$	$I_S=2A, V_{GS}=0V,$	-	29	-	nS
Reverse Recovery Charge <sup>3</sup>	$Q_{rr}$	$V_R=30V, di_F/dt=100A/\mu s$	-	14	-	nC

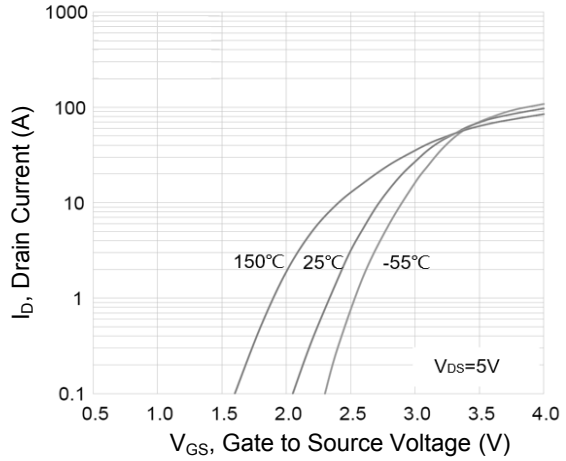
Notes:

- Pulse time of 5 $\mu s$ .
- The dissipated power value will change with the temperature. When it is greater than 25 $^\circ\text{C}$ , the dissipated power value will decrease by 0.55 $^\circ\text{C}/\text{W}$  for every 1 degree of temperature increase.
- Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- Basically unaffected by operating temperature.
- $L=0.5\text{mH}, R_G=25\Omega, V_{DD}=24V, T_J=25^\circ\text{C}$ .

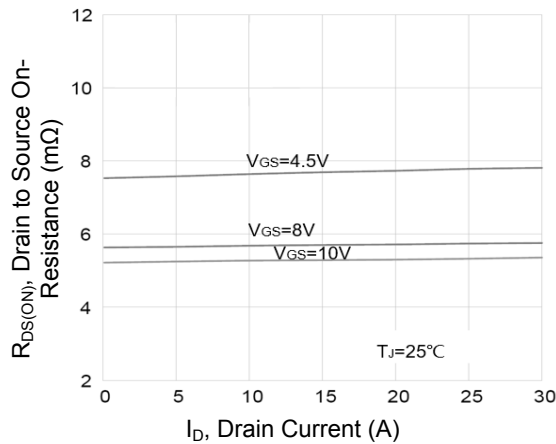
**Typical Electrical and Thermal Characteristic Curves**



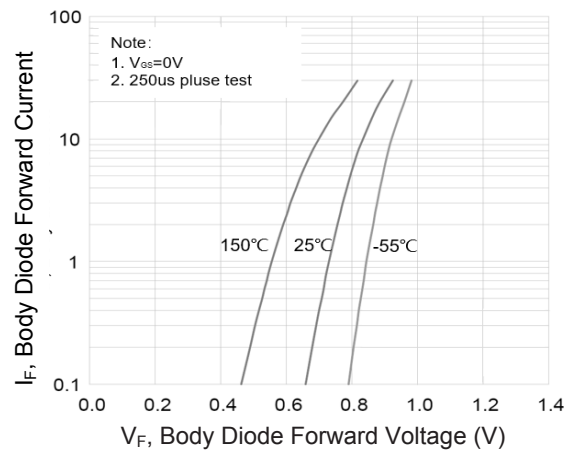
**Figure 1. Typical Output Characteristics**



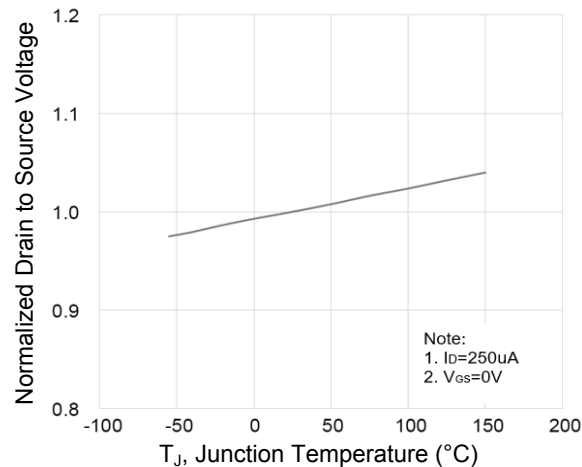
**Figure 2. Transfer Characteristics**



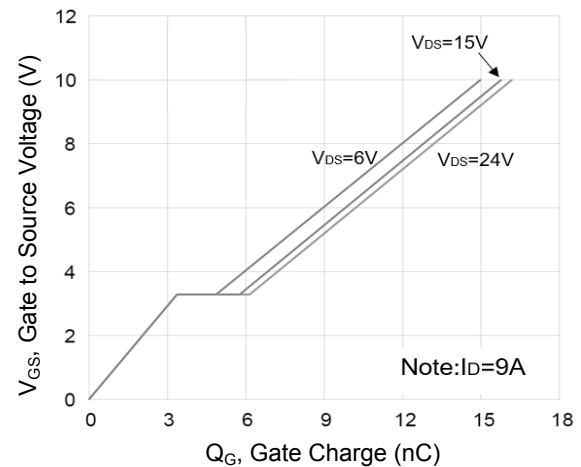
**Figure 3.  $R_{DS(ON)}$  vs. Drain Current**



**Figure 4. Body Diode Characteristics**

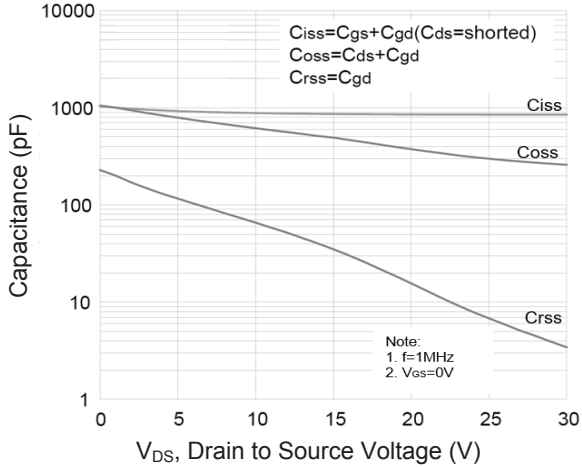


**Figure 5. Normalized  $BV_{DSS}$  vs.  $T_J$**

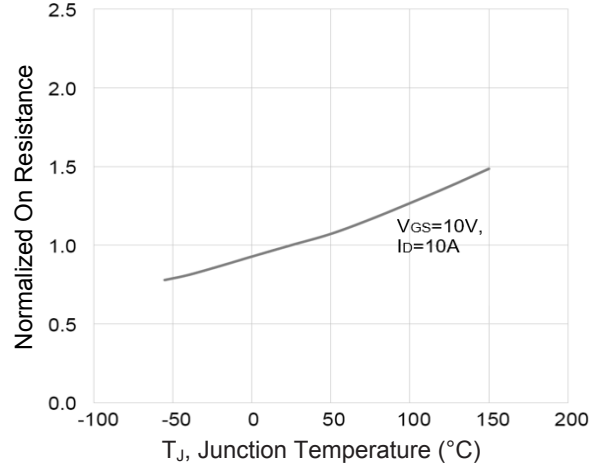


**Figure 6. Gate Charge**

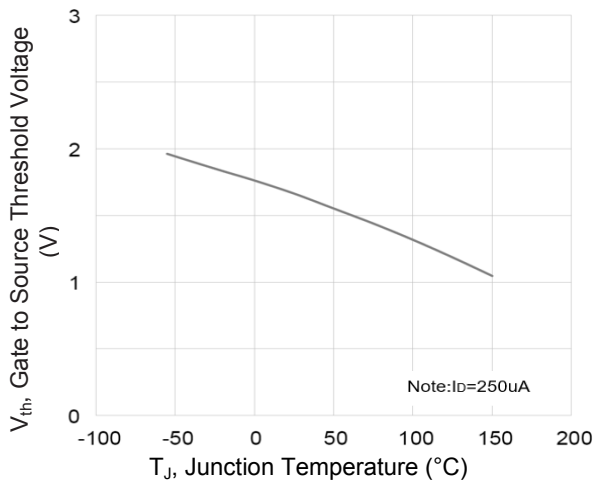
**Typical Electrical and Thermal Characteristic Curves**



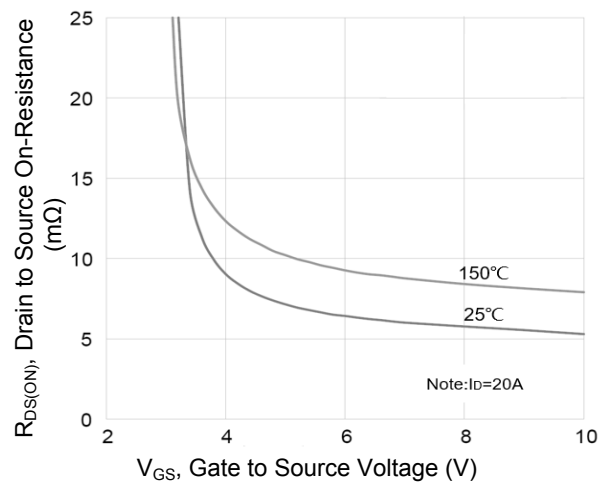
**Figure 7. Capacitance Characteristics**



**Figure 8. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



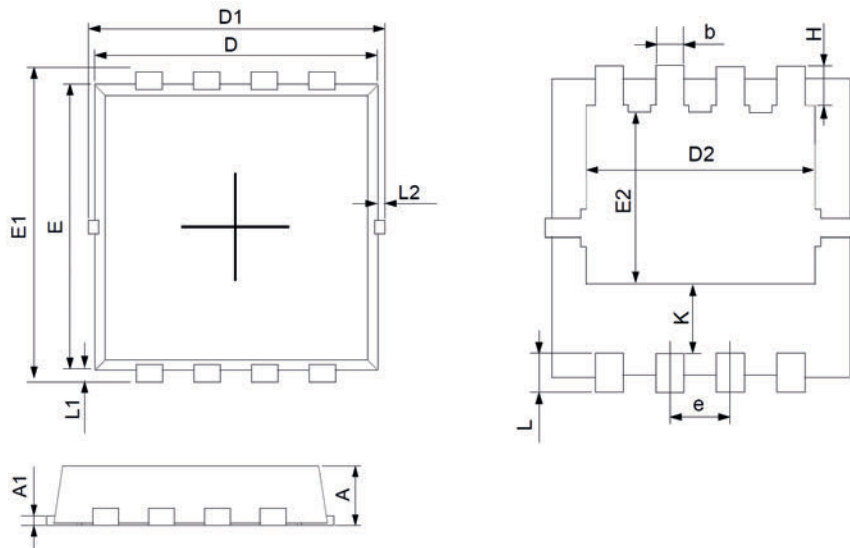
**Figure 9.  $V_{th}$  vs.  $T_J$**



**Figure 10.  $R_{DS(ON)}$  vs. Gate to Source Voltage**



## Package Outline Dimensions (PPAK3x3)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.70	0.90	0.028	0.035
A1	0.14	0.20	0.006	0.008
D	3.05	3.25	0.120	0.128
E	2.90	3.10	0.114	0.122
D1	3.10	3.50	0.122	0.138
D2	2.35	2.50	0.093	0.098
E1	3.10	3.50	0.122	0.138
E2	1.64	1.84	0.065	0.072
b	0.25	0.35	0.010	0.014
k	0.59	0.79	0.023	0.031
e	0.55	0.75	0.022	0.030
E4	3.34	3.92	0.131	0.154
L	0.25	0.55	0.010	0.022
L1	0.10	0.20	0.004	0.008
H	0.32	0.52	0.013	0.020

## Order Information

Device	Package	Marking	Carrier	Quantity
GSGN6R204	PPAK3x3	N6R204	Tape & Reel	5,000pcs / Reel